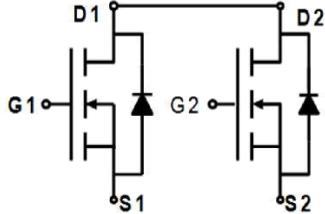
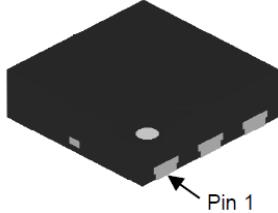


FH8820

N- Channel Enhancement Mode

General Description	Product Summary
FH8820 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.	V_{DS} 20 V I_D (at $V_{GS}=4.5V$) 6.0A $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 29mΩ $R_{DS(ON)}$ (at $V_{GS} = 2.5V$) < 34mΩ

DFN 2*2-6L			
			
Schematic diagram	Marking and pin Assignment (The bottom center metal pad is D1/D2)		DFN 2*2-6L top view

Absolute Maximum Ratings TA=25°C unless otherwise noted				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	20	V	
Gate-Source Voltage	V_{GS}	± 12	V	
Drain Current-Continuous @ $T_J=25^\circ C$	I_D	6	A	
Pulsed ^b	I_{DM}	24	A	
Drain-Source Diode Forward Current ^a	I_S	2.5	A	
Maximum Power Dissipation ^a	P_D	1.5	W	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C	

Thermal Characteristics					
Parameter	Symbol	Typ	Max	Units	
Maximum Junction-to-Ambient ^a	$t \leq 10s$	$R_{\theta JA}$	37	45	°C/W

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.45	0.65	1.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =4.5A	-	19	22.5	mΩ
		V _{GS} =2.5V, I _D =3.5A	-	24	28	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =7A	-	17.7	-	S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =8V, V _{GS} =0V, F=1.0MHz	-	802	-	pF
Output Capacitance	C _{oss}		-	153	-	pF
Reverse Transfer Capacitance	C _{rss}		-	122	-	pF
Switching Characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V, I _D =1A V _{GS} =4.5V, R _{GEN} =10Ω , R _L =10Ω	-	18	-	ns
Turn-on Rise Time	t _r		-	5	-	ns
Turn-Off Delay Time	t _{d(off)}		-	43.8	-	ns
Turn-Off Fall Time	t _f		-	20	-	ns
Total Gate Charge	Q _g	V _{DS} =10V, I _D =4A, V _{GS} =4.5V	-	10.5	-	nC
Gate-Source Charge	Q _{gs}		-	2	-	nC
Gate-Drain Charge	Q _{gd}		-	2.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1.7A	-	-	1.2	V

Notes:

- a. Surface Mounted on FR4 Board ,T<10 sec ;
- b. Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.
- c. Guaranteed by Design, not subject to production testing.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

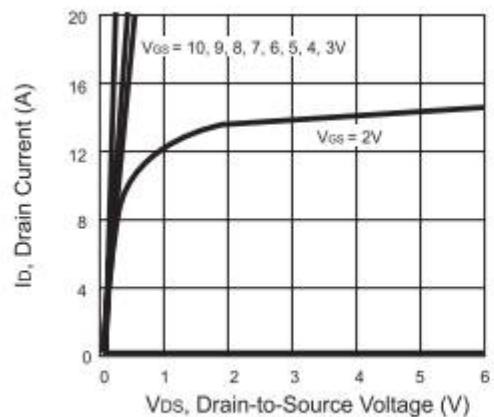


Figure 1. Output Characteristics

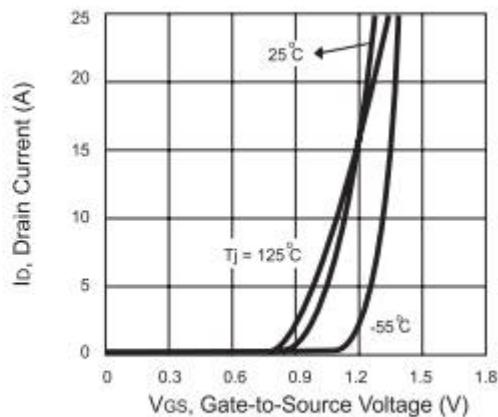


Figure 2. Transfer Characteristics

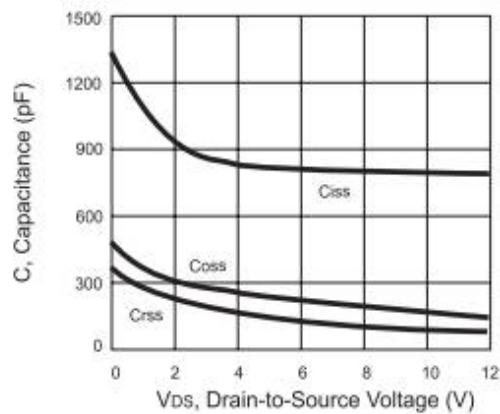


Figure 3. Capacitance

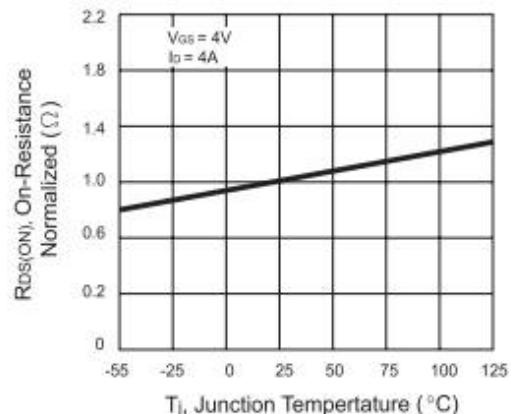


Figure 4. On-Resistance Variation with Temperature

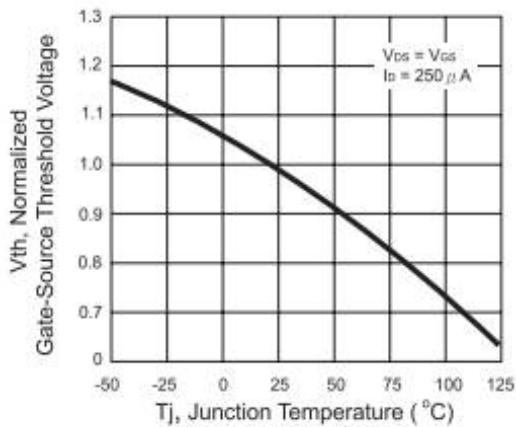


Figure 5. Gate Threshold Variation with Temperature

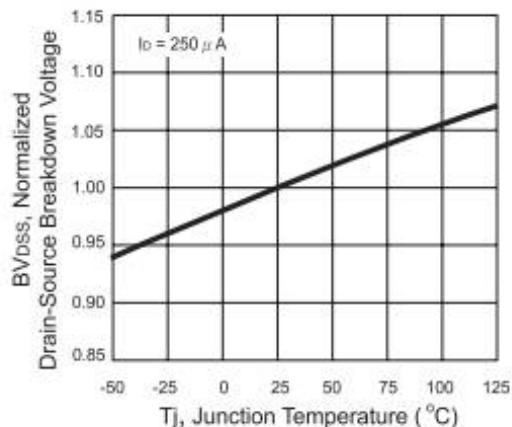


Figure 6. Breakdown Voltage Variation with Temperature

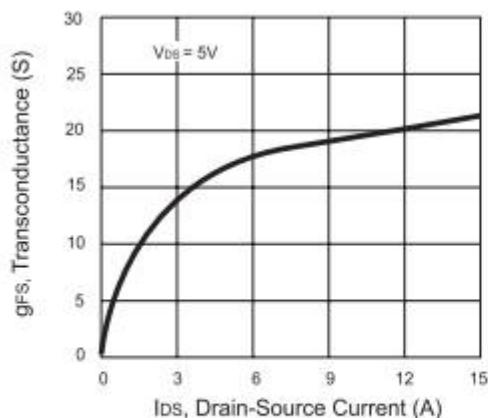


Figure 7. Transconductance Variation with Drain Current

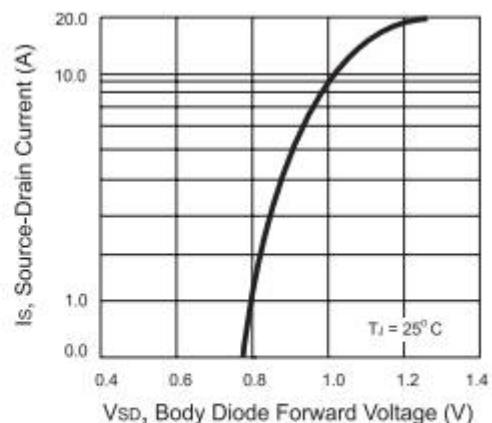


Figure 8. Body Diode Forward Voltage Variation with Source Current

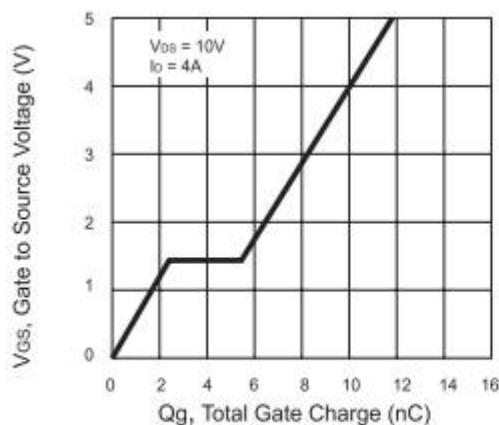


Figure 9. Gate Charge

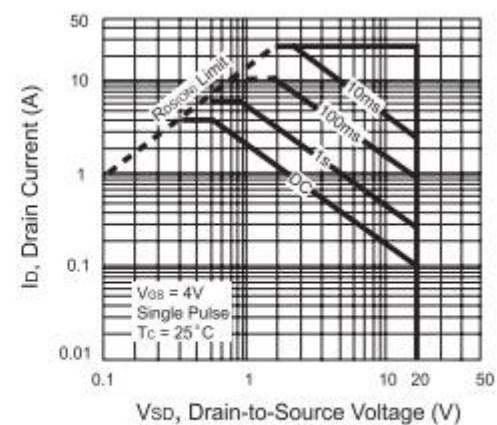


Figure 10. Maximum Safe Operating Area

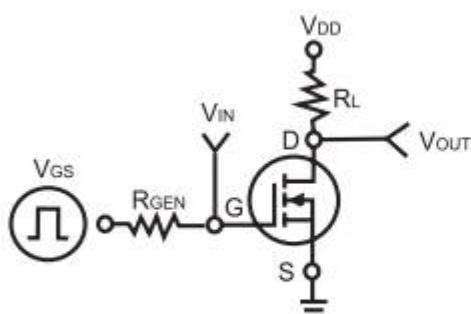


Figure 11. Switching Test Circuit

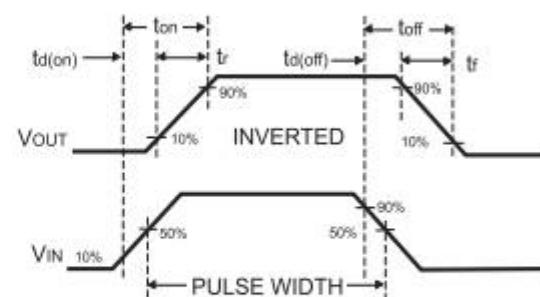


Figure 12. Switching Waveforms

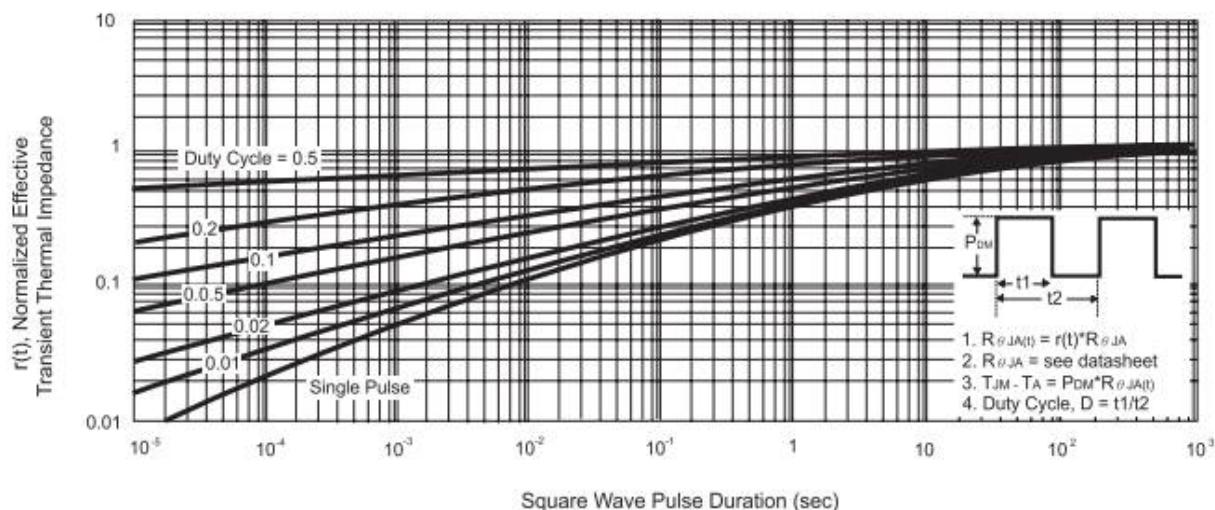
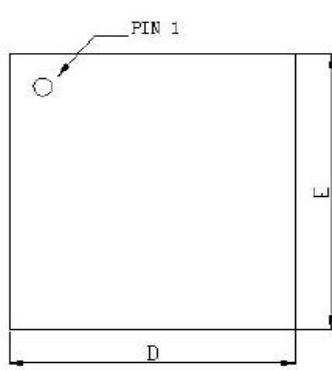


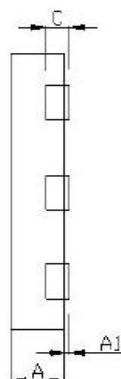
Figure 13. Normalized Thermal Transient Impedance Curve

封装尺寸

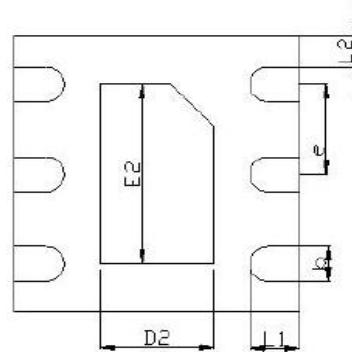
DFN 2x2-6L产品尺寸规格图



Top view



Side view



Bottom view

Symbol	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.02	0.000	0.001	0.002
b	0.22	0.25	0.28	0.009	0.010	0.011
C	0.20			0.008		
D	1.90	2.00	2.10	0.076	0.080	0.084
D2	0.77	0.80	0.83	0.030	0.032	0.033
E	1.90	2.00	2.10	0.076	0.080	0.084
E2	1.27	1.30	1.33	0.050	0.052	0.053
e	0.650 BSC			0.026		
L1	0.30	0.35	0.40	0.012	0.014	0.016
L2	0.100	0.150	0.200	0.004	0.006	0.008